

CMS MTD Barrel Timing Layer: Precision Timing at the HL-LHC

Badder Marzocchi¹, on behalf of the CMS Collaboration
¹Northeastern University (Boston, US)

26-30 July 2021



Compact Muon Solenoid

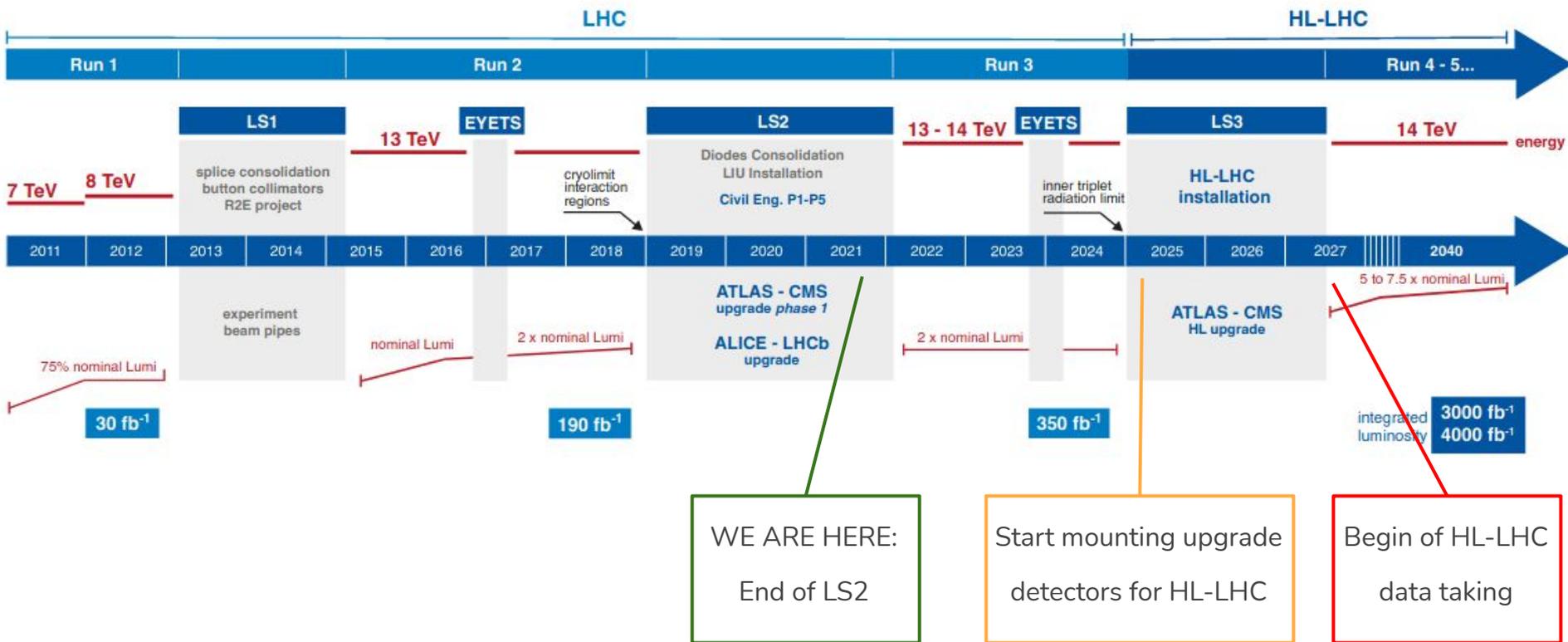
EPS-HEP Conference 2021

European Physical Society conference on high energy physics 2021

Online conference, July 26-30, 2021

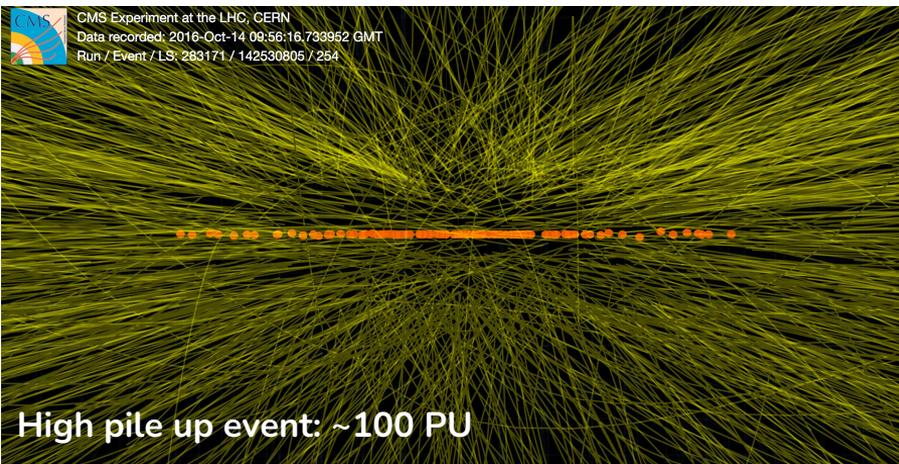


High Luminosity LHC: Schedule

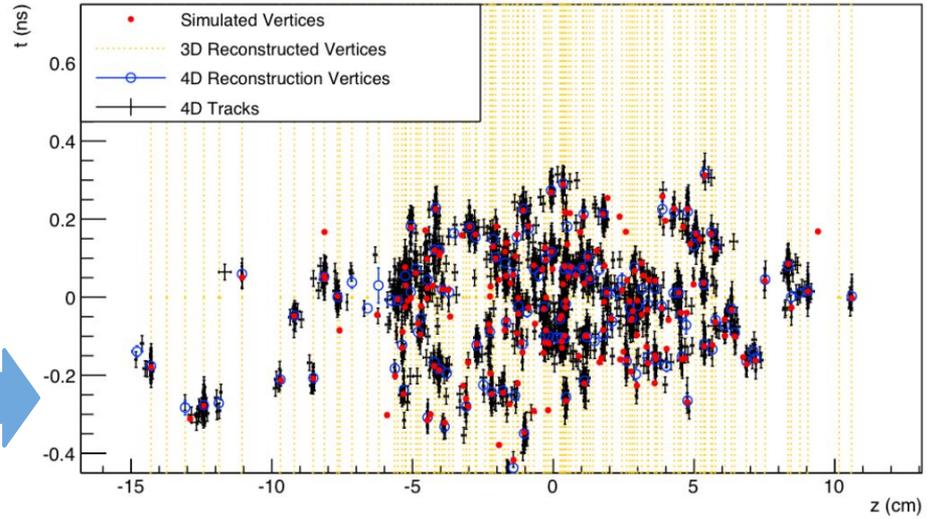


High Luminosity LHC: Challenges

- **High number of collisions per bunch crossing:**
 - Nominal scenario: $5 \times 10^{34} \text{ cm}^{-2} \text{ s}^{-1}$, ~ 140 PU
 - Ultimate scenario: $7.5 \times 10^{34} \text{ cm}^{-2} \text{ s}^{-1}$, ~ 200 PU
- **High pile up and radiation damage to detectors:**
 - Degradation of energy reconstruction and particle identification

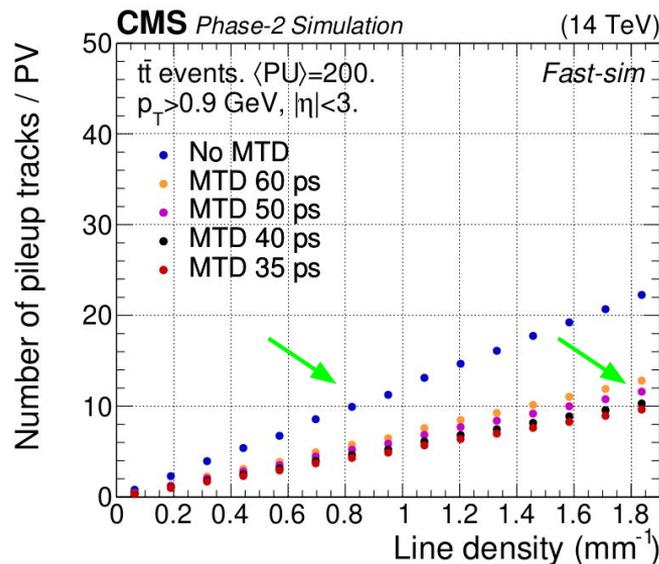


High pile up event: ~ 100 PU

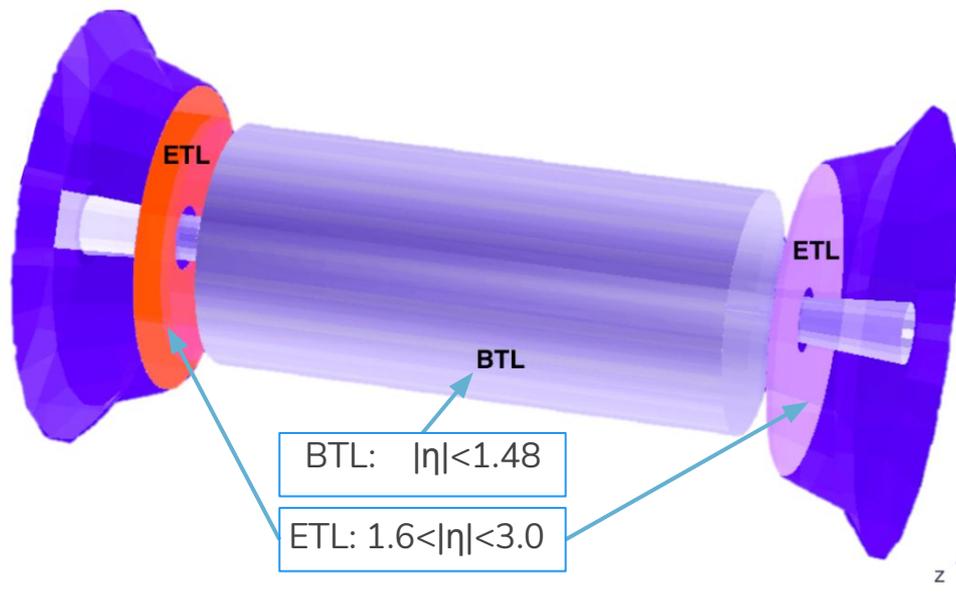


- **Timing information can be exploited to reject tracks coming from the pile up \rightarrow Enable 4D reconstruction of vertices**
- **Proposed Minimum Ionizing Particle (MIP) Timing Detector (MTD):**
 - Provide 30-40 ps time resolution for MIPs (beginning of HL-LHC)

- **Impact on the CMS physics:**
 - Improve particle isolation, vertex identification (b-tagging, photons, long lived particles) and p_T^{miss} reconstruction
 - Time of flight (TOF) detector for charged particles identification, helping Heavy Ion Physics and Flavor Physics
- Recover the effective background conditions close to Phase-1 operations and **maintain excellent performance of CMS detector during HL-LHC**

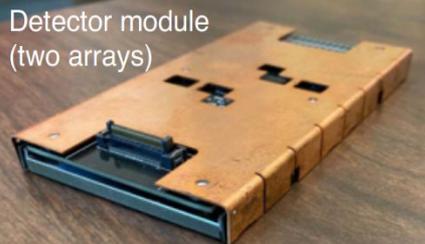


| | Signal increase (%) | | Expected significance | |
|-------------------|---------------------|---------|-----------------------|------|
| | BTL | BTL+ETL | No MTD | MTD |
| Di-Higgs decay | | | | |
| bbbb | 13 | 17 | 0.88 | 0.95 |
| bb $\tau\tau$ | 21 | 29 | 1.3 | 1.6 |
| bb $\gamma\gamma$ | 13 | 17 | 1.7 | 1.9 |
| bbWW | | | 0.53 | 0.58 |
| bbZZ | | | 0.38 | 0.42 |
| Combined | | | 2.4 | 2.7 |

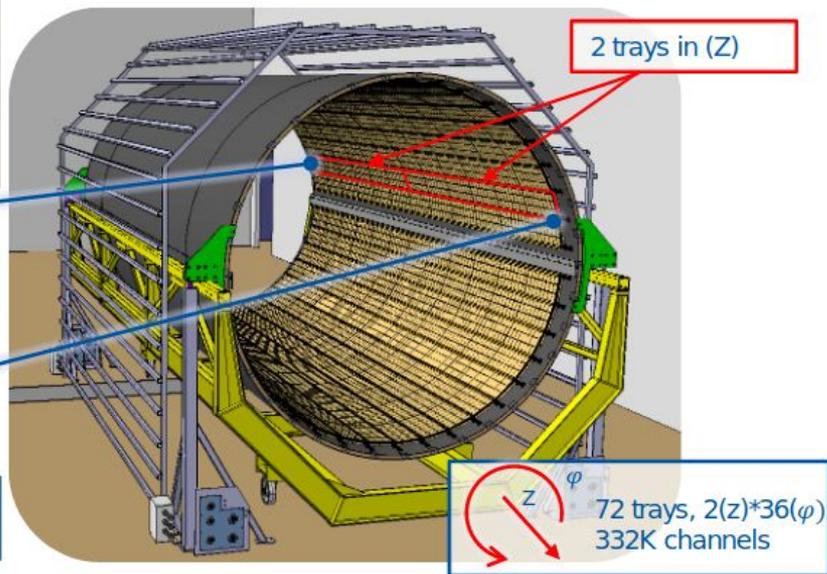
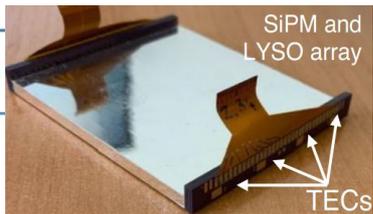


- Split into two main sub-systems:
 - Barrel Timing Layer (BTL)
 - Endcap Timing layer (ETL)
- MTD is required to last throughout the HL-LHC era (~3000/fb)
- BTL and ETL will experience differing radiation dose through their lifetime (FLUKA estimates):
 - BTL : $1.65 \times 10^{14} - 1.90 \times 10^{14}$ neq/cm²
 - ETL : $1.50 \times 10^{14} - 1.60 \times 10^{15}$ neq/cm²

- Different technologies must be chosen:
 - BTL : LYSO:Ce crystal bars coupled to SiPM readout
 - ETL : Si with internal gate (LGAD)



BTL Module
2x16 LYSO Crystals
2*32 Channels



- Thin (~40 mm), cylindrical layer housed in the Tracker/ECAL interface
- **Sensor technology: LYSO:Ce crystal scintillators read by SiPMs at both ends**
- **Read out by a dedicated ASIC, TOFHIR (Time-of-flight, High Rate) chip** which delivers precision timing information
- **Nominal operating temperature -45°C** to limit the noise induced time jitter

- ❑ Total active area of 38 m²
- ❑ Z = 5.2 m, R = 1148 mm and $|\eta| < 1.48$
- ❑ Total power requirement of ~30 kW
- ❑ -35°C with CO₂ and -10°C with thermo-electric cooler (TEC)

LYSO:Ce:

- ❑ High density (7.1 g/cm³): most probable value of energy deposit by a MIP ~ 0.86 MeV/mm
- ❑ High light yield (~ 40000 photons/ MeV)
- ❑ Fast scintillation rise time (< 100 ps)
- ❑ Short decay time (~ 40 ns)
- ❑ Non-hygroscopic

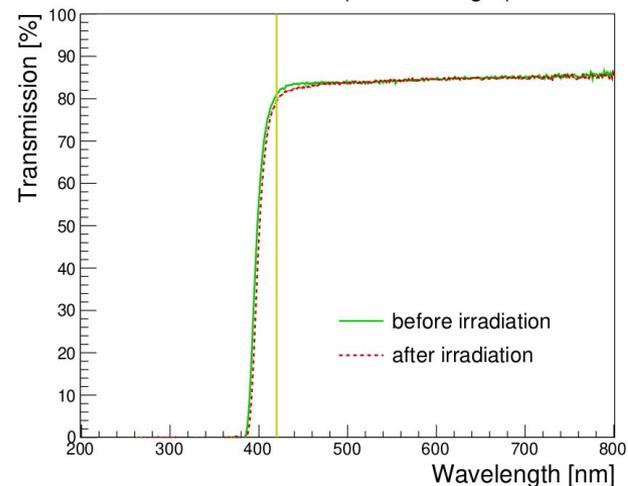
SiPMs:

- ❑ Compact, robust and insensitive to magnetic fields
- ❑ Photo-detection efficiency (PDE): 20-40%, with optimal cell size of 15 μm
- ❑ Good radiation tolerance

● Crystals:

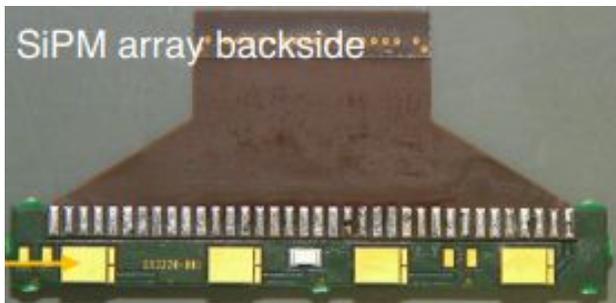
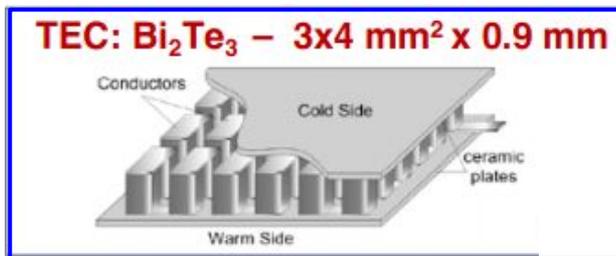
- **Dimension:** $\sim 3 \times 3 \times 57$ mm³ with η -dependent thickness
- **Scintillation light at 420 nm** wavelength, matching SiPMs sensitivity
- **Very high radiation tolerance**
→ verified with 24 GeV protons fluence of 2×10^{13} cm⁻²

LYSO:Ce bar (50 mm length)



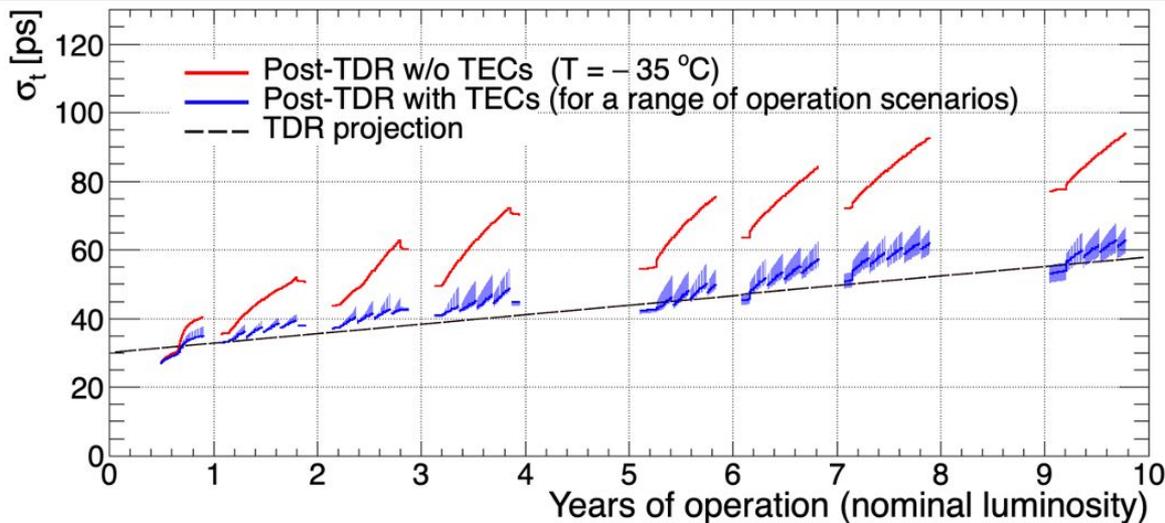
- **Challenges:**

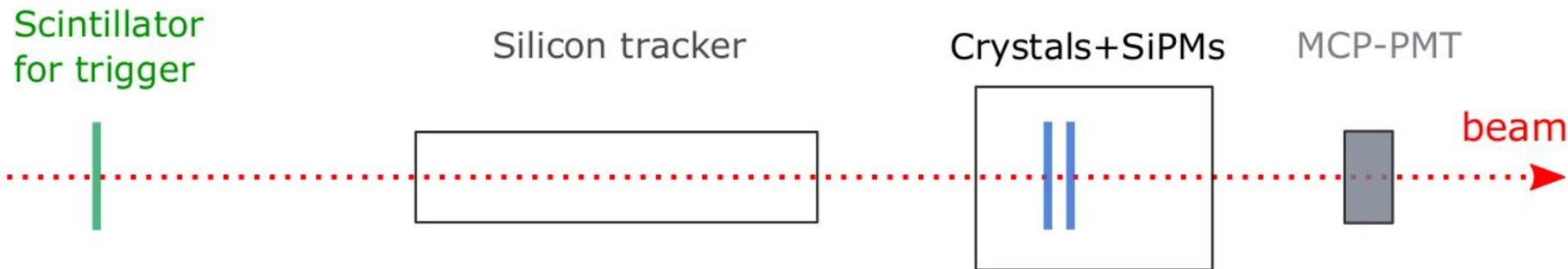
- Increase of dark count rate (DCR) with radiation damage and temperature
- Linear drift of breakdown voltage with radiation



- **Solutions:**

- Dedicated noise cancellation circuit in the ASIC (TOFHIR)
- Annealing the SiPMs to about 40°C during shutdown
- Use thermoelectric coolers (TECs) to reduce SiPMs operating temperature

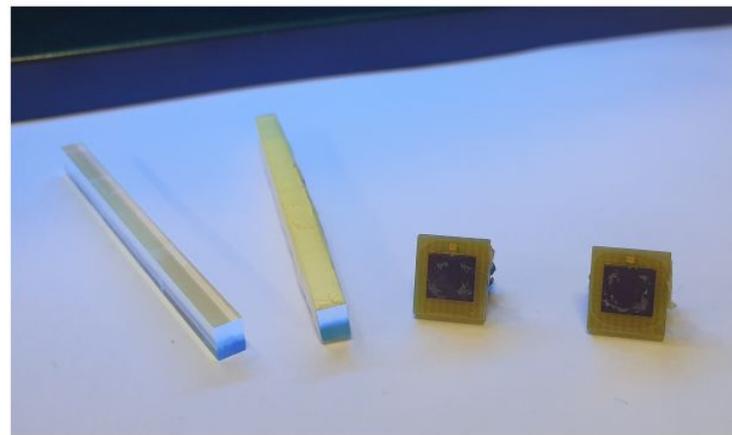




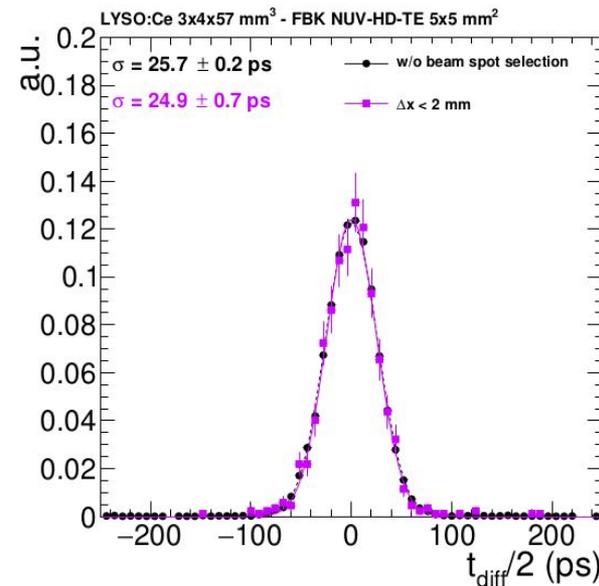
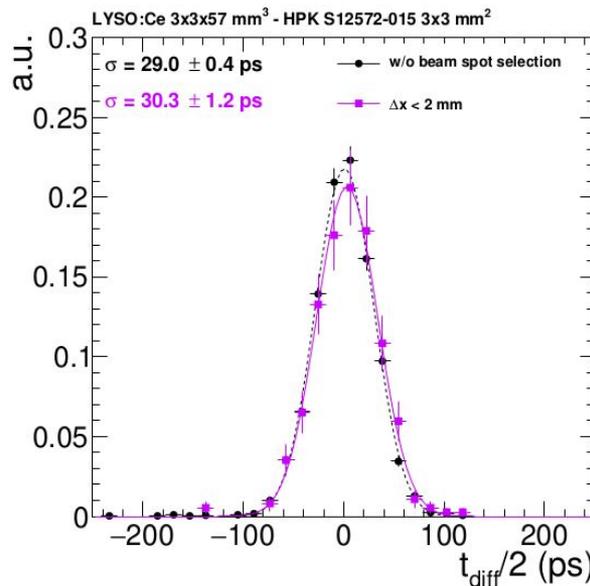
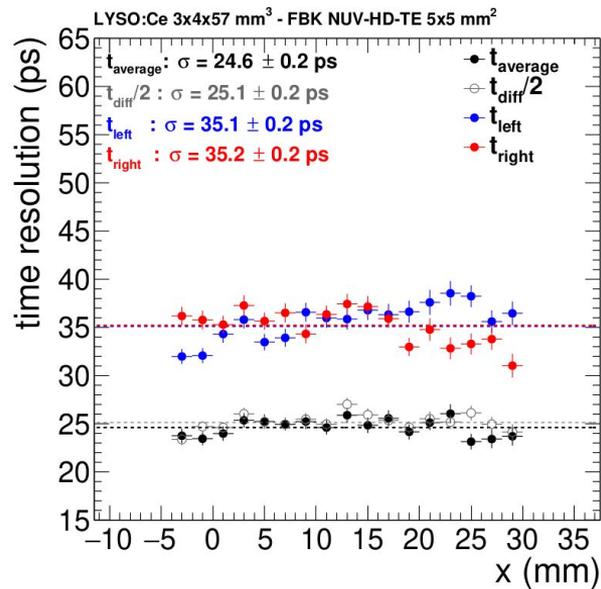
→ Performed at Fermilab Test Beam Facility (FTBF), using 120 GeV protons

Setup:

- Trigger based on a 10 cm² scintillation counter
- Silicon tracker telescope spatial information (X-Y)
- Micro Channel Plate (MCP) PMT for time reference
- LYSO:Ce + SiPMs (different prototypes) at 25°C, with ad-hoc read out electronics



JINST: [10.1088/1748-0221/16/07/P07023](https://doi.org/10.1088/1748-0221/16/07/P07023)



Time resolution estimation:

- $(t_{\text{left}} + t_{\text{right}})/2 - t_{\text{MCP}} = t_{\text{average}}$
- $t_{\text{left}} - t_{\text{right}} = t_{\text{diff}}$
- $t_{\text{left}} - t_{\text{MCP}}$
- $t_{\text{right}} - t_{\text{MCP}}$

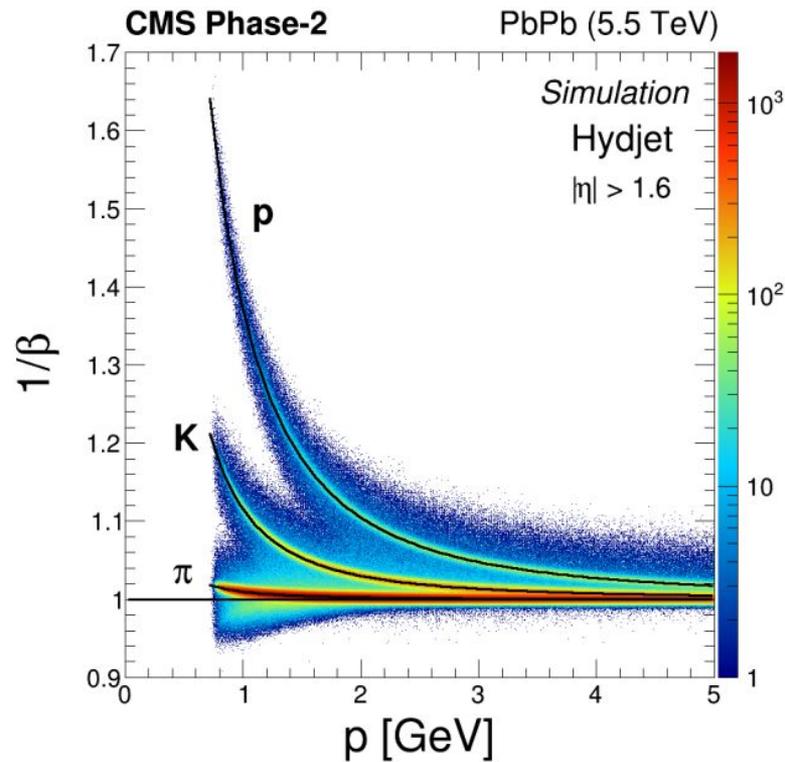
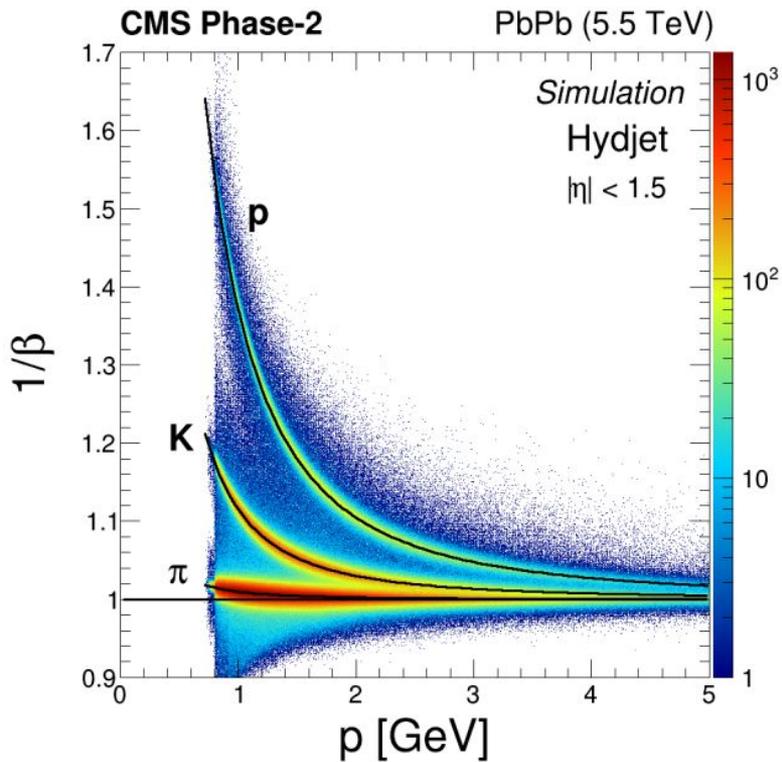
Test various SiPM prototypes:

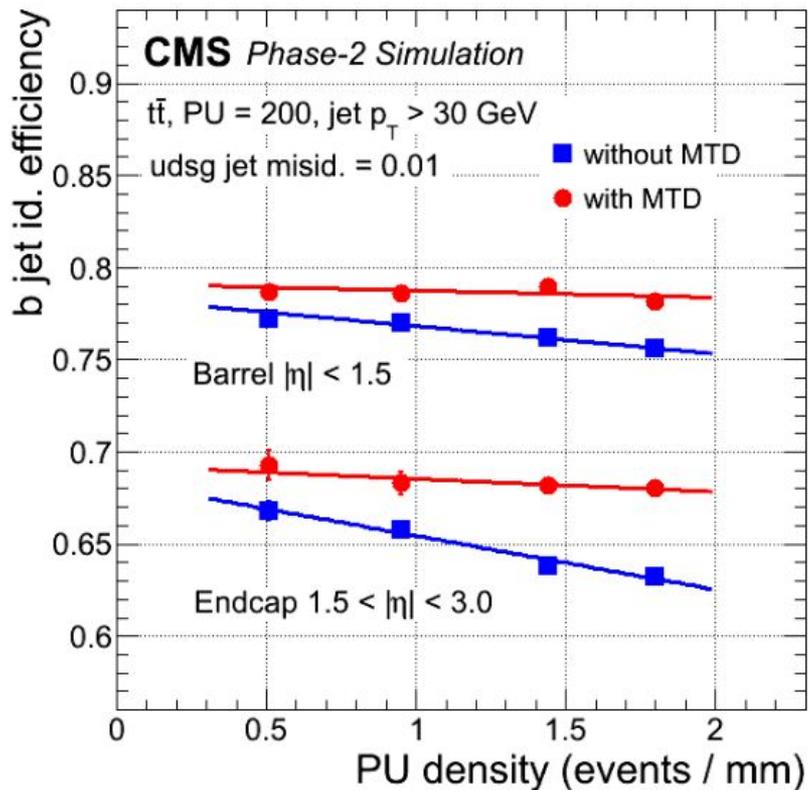
- HPK S12572-015 (3x3 mm² area)
- FBK NUV-HD-TE (5x5 mm² area)

Target time resolution achieved

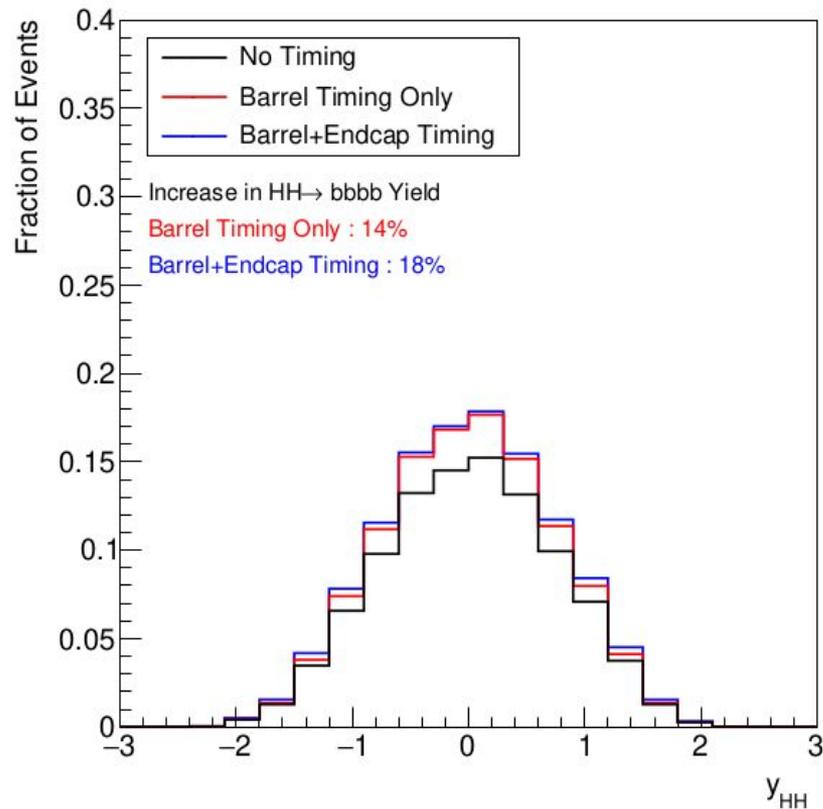
- Precision time measurements of MIP particles:
 - Help mitigating pileup during HL-LHC data taking
 - Improve particle isolation, vertex identification, p_T^{miss} reconstruction and time of flight measurement
- Target time resolution of 30 ps has been achieved in test beam characterization of the current BTL sensor technology: LYSO:Ce readout by SiPMs
- Prototype testing ongoing :
 - Optimize end of life (end of HL-LHC operation) performance of BTL sensor modules with irradiated SiPMs, coupled to thermoelectric coolers
 - Test ASIC chip (TOFHIR) and readout unit

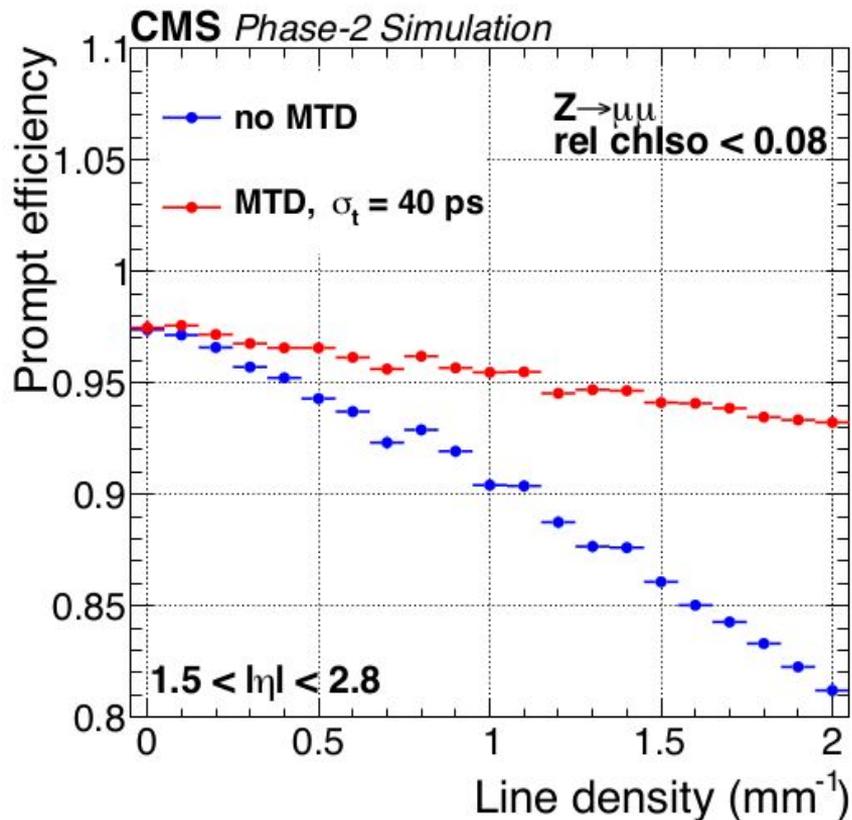
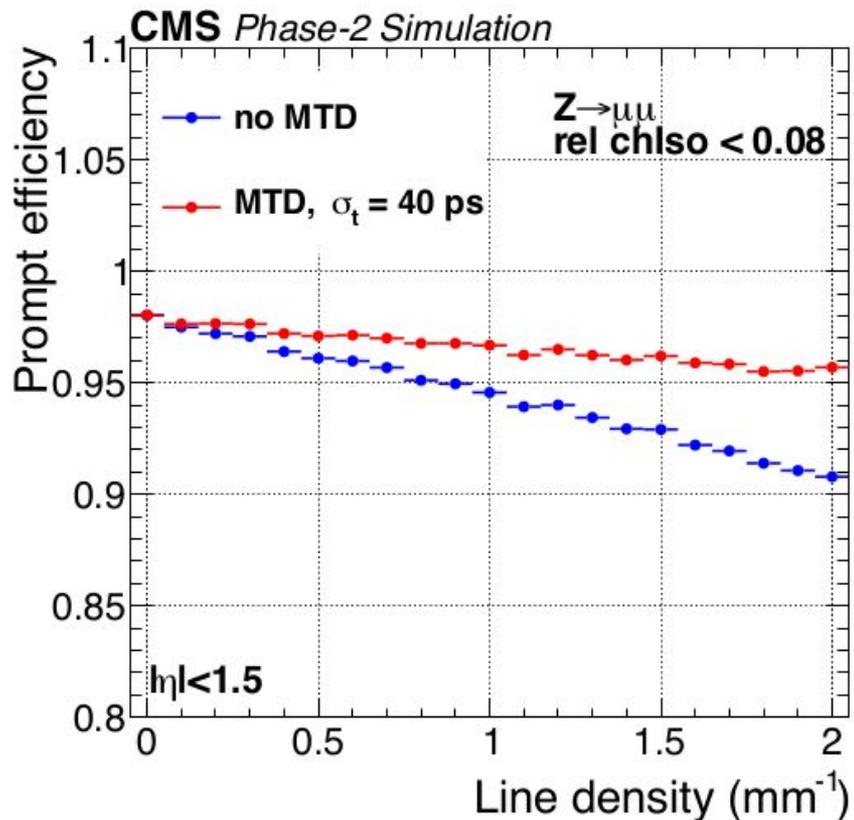
BACKUP





HH \rightarrow bbbb (200 Pileup Distribution)





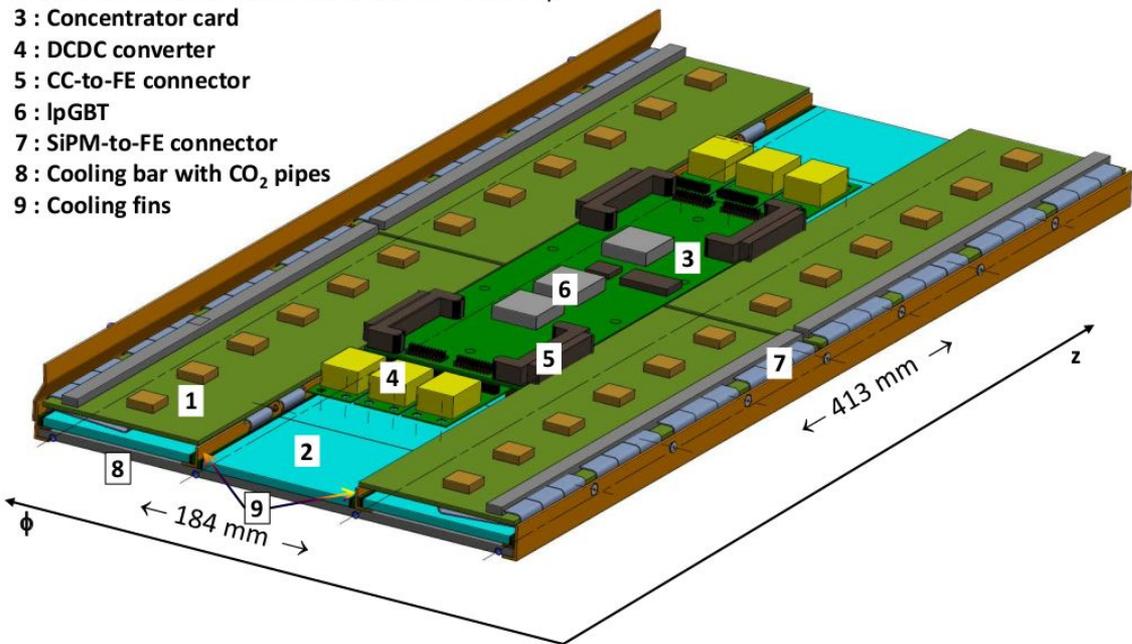
| $ \eta $ region | 0–0.7 | 0.7–1.1 | 1.1–1.48 |
|---|-----------------------|-----------------------|-----------------------|
| Readout unit ID within tray | 1–2 | 3–4 | 5–6 |
| Crystal thickness, t [mm] | 3.75 | 3.0 | 2.4 |
| $\langle t_{\text{slant}} \rangle$ [mm] | 4.0 | 4.3 | 4.6 |
| SiPM active area [mm ²] | 11.2 | 9.0 | 7.2 |
| $\langle \Phi_{\text{neq}}^{\text{tot}} (3000 \text{ fb}^{-1}) \rangle$ [cm ⁻²] | 1.65×10^{14} | 1.75×10^{14} | 1.85×10^{14} |

| | Module | RU | Tray | Total |
|--------------------|--------|-----|------|--------|
| Channels (SiPMs) | 32 | 768 | 4608 | 331776 |
| Crystals | 16 | 384 | 2304 | 165888 |
| ASICs | 1 | 24 | 144 | 10368 |
| Modules | - | 24 | 144 | 10368 |
| Readout units (RU) | - | - | 6 | 432 |
| Trays | - | - | - | 72 |

| LYSO:Ce crystal parameter | Specification | Spread (rms) |
|---|-------------------------|---------------|
| Light output / end | > 6000 photons/MeV | < 5% |
| LY(10ns)/LY(200ns) | > 20 % | < 3% |
| LY(200ns)/LY(2000ns) | > 95 % | < 3% |
| Decay time | < 43 ns | < 3% |
| Rise time | < 200 ps | < 3% |
| Density | > 7.1 g/cm ³ | < 2% |
| Refractive index | 1.82 | – |
| Radiation tolerance | | |
| Loss of light output | < 5% | < 5% |
| Induced absorption coeff., μ_{ind} | < 3 m ⁻¹ | < 5% |
| Dimensions | | |
| | Specification | Tolerance |
| Length [mm] | 57.0 | +0.00 / –0.03 |
| Width [mm] | 3.12 | +0.00 / –0.03 |
| Height [mm] | 3.75 / 3.0 / 2.4 | +0.00 / –0.03 |
| Surface polishing | < 15 nm | |

| SiPM parameter | Specification | FBK-NUV-HD | HPK-S12572 | HPK-HDR2 |
|--|------------------------|--------------------------------|--------------------------------|--------------------------------|
| Active area | – | $\sim 9 \text{ mm}^2$ | $\sim 9 \text{ mm}^2$ | $\sim 9 \text{ mm}^2$ |
| Cell pitch | $< 20 \mu\text{m}$ | $15 \mu\text{m}$ | $15 \mu\text{m}$ | $15 \mu\text{m}$ |
| Cell recovery time | $< 10 \text{ ns}$ | 7 ns | 8.5 ns | $< 10 \text{ ns}$ |
| Capacitance | $< 600 \text{ pF}$ | 530 pF | 295 pF | 585 pF |
| Number of cells | $> 20\text{k}$ | $\sim 40\text{k}$ | $\sim 40\text{k}$ | $\sim 40\text{k}$ |
| $V_{\text{br}} (-30^\circ\text{C})$ | – | 34.2 V | 63.0 V | 35.8 V |
| dV_{br}/dT | – | $41 \text{ mV}/^\circ\text{C}$ | $59 \text{ mV}/^\circ\text{C}$ | $37 \text{ mV}/^\circ\text{C}$ |
| $\delta V_{\text{br}}/10^{13} n_{\text{eq}}/\text{cm}^2$ | $\leq 0.2 \text{ V}$ | $< 0.1 \text{ V}$ | 0.2 V | $< 0.1 \text{ V}$ |
| DCR-T coefficient | – | 1.76 | 1.90 | 1.79 |
| ENF | < 1.1 | < 1.05 | 1.07 | < 1.05 |
| Parameters after 3000 fb⁻¹ | | | | |
| Optimal OV | $> 1\text{V}$ | 1.6 V | 1.5 V | 1.2 V |
| PDE | – | 15% | 13% | 23% |
| Current/device | – | 1.32 mA | 0.77 mA | 1.30 mA |
| Static power consumption | $\leq 50 \text{ mW}$ | 50 mW | 50 mW | 50 mW |
| Gain | $\geq 1.3 \times 10^5$ | 2.1×10^5 | 1.45×10^5 | 1.55×10^5 |
| DCR/SiPM | – | 42 GHz | 37 GHz | 55 GHz |
| $\text{PDE}/\sqrt{\text{DCR}}$ | ≥ 2.0 | 2.3 | 2.1 | 3.1 |

- 1 : TOFHIR board with 6 ASICs
- 2 : LYSO array with 16 LYSO bars, bars oriented in ϕ
- 3 : Concentrator card
- 4 : DCDC converter
- 5 : CC-to-FE connector
- 6 : lpGBT
- 7 : SiPM-to-FE connector
- 8 : Cooling bar with CO₂ pipes
- 9 : Cooling fins



- TOFHIR (Time-of-flight, High Rate) ASIC chip:
 - Discrimination of the leading edges
 - Time measurement with a TDC
- 6 ASICs are mounted on a front end board
- 4 front-end boards plugged into a Concentrator Card:
 - Provide low voltage, bias voltage
 - 3 lpGBTs transfer data and control signals
- The ASICs, FE, CC, and associated power supplies constitute the RU, which supports 768 SiPMs